

Press Release

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Rehm Thermal Systems at Bondexpo 2026: Precise Dispensing Meets Efficient UV LED Curing

When the industry meets at Bondexpo in Stuttgart from 6 to 8 October 2026, Rehm Thermal Systems will also be presenting innovative equipment solutions for precise dispensing, potting and curing processes. In hall 6 at booth 6505, the company will showcase the **ProtectoXC** and the **RDS UV LED** – two powerful systems designed for flexible, efficient and reproducible production processes.

Bondexpo covers the entire process chain for adhesive bonding, potting, sealing and foaming. This makes the trade fair an ideal platform for Rehm Thermal Systems to demonstrate solutions that combine highly precise material application with powerful curing technology.



ProtectoXC: Flexible Dispensing Solution for Dispensing, Bonding and Potting

With the **ProtectoXC**, Rehm is presenting a compact and versatile platform for demanding dispensing and application tasks. At Bondexpo, the focus will be on applications in the areas of dispensing, bonding and potting.

The system enables precise and reproducible processing of a wide range of materials and is suitable for numerous applications in modern electronics and assembly production. These include the selective application of adhesives, the dispensing of potting compounds as well as various bonding and underfill processes.

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Thanks to its flexible system configuration, different application methods and materials can be processed reliably. Applications such as globe top, dam & fill and flip-chip underfill can be implemented just as effectively as the selective or contour-accurate application of adhesive and potting materials.



To ensure a high level of repeatability and process stability, the ProtectoXC features functions such as automatic needle measurement. Application tools can therefore be checked and, where necessary, automatically corrected. Heated nozzles also help maintain a constant material temperature and therefore stable dispensing conditions.

Operation and programming are carried out via the ViCON Protecto software with a modern touch interface. This allows even more complex dispensing processes to be set up clearly and adapted to different products and applications.

RDS UV LED: Fast Curing with Significantly Reduced Energy Consumption

As its second exhibit, Rehm will present the **RDS UV LED** at Bondexpo. The system has been developed for the reliable curing of UV-reactive adhesives, potting compounds and other UV-curing materials and combines short process times with high energy efficiency.

The stationary full-area exposure ensures homogeneous illumination of the entire assembly and supports reproducible curing even with demanding geometries. Four individually controllable UV LED segments make it possible to adapt the exposure flexibly to the respective product and process.

A key advantage of LED technology is its immediate readiness for use without any warm-up time. At the same time, energy consumption can be significantly reduced compared with conventional UV lamps. Depending on the application, exposure times are only a few seconds.

Since UV LED technology operates without conventional infrared radiation, temperature-sensitive assemblies and components in particular benefit from reduced thermal stress.

The RDS UV LED also offers a high degree of flexibility when it comes to material selection. In addition to materials specifically optimised for LED applications, a wide range of UV-reactive systems can be processed. This makes the system suitable for a broad range of industrial applications involving bonding, potting and coating.

Dispensing and Curing as an Integrated Process

With the combination of **ProtectoXC** and **RDS UV LED**, Rehm will demonstrate at Bondexpo how two technologies can complement each other within modern bonding, dispensing and potting processes. Precise material application, flexible process design and efficient UV curing provide the basis for stable and reproducible production processes.

Visitors to Bondexpo will have the opportunity to experience both systems up close at the Rehm booth and discuss individual applications, materials and process requirements with Rehm experts.

Rehm Thermal Systems at Bondexpo 2026

6 to 8 October 2026

Messe Stuttgart

Booth 6505

Further information:

www.rehm-group.com

www.bondexpo-messe.de

Please find attached the following image materials: ProtectoXC, RDS UV LED, Conformal Coating Line LED (*Pictures: Rehm Thermal Systems*)

About Rehm Thermal Systems

Rehm Thermal Systems is an expert in joining technologies for electronics manufacturing. With innovative system solutions for soldering, drying, and coating, we enable our customers to create reliable connections on electronic assemblies – tailor-made, process-safe, and future-oriented.

Since 1990, we have been developing and manufacturing energy-efficient production equipment to the highest quality standards at our headquarters in Germany and at an additional production site in China. Our global subsidiaries and distributors provide customized solutions and competent service – wherever electronics are made.

Create your Connections – with Rehm, you shape the joining technology of tomorrow.